

Title (en)

METHOD FOR MANUFACTURING BONDED WAFER

Title (de)

HERSTELLUNGSVERFAHREN FÜR GEBUNDENE WAFER

Title (fr)

PROCÉDÉ DE FABRICATION D'UNE PLAQUETTE LIÉE

Publication

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Application

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Abstract (en)

[origin: EP2251895A1] The present invention provides a method for manufacturing a bonded wafer, the method including at least the steps of implanting at least one type of gas ion selected from a hydrogen ion and a rare gas ion from a surface of a bond wafer to form an ion-implanted layer in the wafer, bonding an ion-implanted surface of the bond wafer to a surface of a base wafer directly or through an insulator film, and then delaminating the bond wafer at the ion-implanted layer to fabricate a bonded wafer, wherein a plasma treatment is applied to a bonding surface of at least one of the bond wafer and the base wafer to grow an oxide film, a treatment of etching the grown oxide film is carried out, and then bonding to the other wafer is performed. As a result, there can be provided the method for manufacturing a bonded wafer, the method enabling preventing defects from being generated in the thin film of the bonded wafer by reducing particles on the bonding surface and performing strong bonding when effecting bonding directly or through the insulator film.

IPC 8 full level

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